

# TinyLogic HST 2-Input AND Gate

## NC7ST08

### Description

The NC7ST08 is a single 2-Input high performance CMOS AND Gate, with TTL-compatible inputs. Advanced Silicon Gate CMOS fabrication assures high speed and low power circuit operation. ESD protection diodes inherently guard both inputs and output with respect to the  $V_{CC}$  and GND rails. High gain circuitry offers high noise immunity and reduced sensitivity to input edge rate. The TTL-compatible inputs facilitate TTL to NMOS / CMOS interfacing. Device performance is similar to MM74HCT but with 1/2 the output current drive of HC / HCT.

### Features

- Space Saving SOT23-5, SC-74A and SC-88A 5-Lead Package
- Ultra Small MicroPak<sup>™</sup> Leadless Package
- High Speed:  $t_{PD} = 6 \text{ ns}$  (Typ),  $V_{CC} = 5 \text{ V}$ ,  $C_L = 15 \text{ pF}$ ,  $T_A = 25^\circ\text{C}$
- Low Quiescent Power:  $I_{CC} < 1 \mu\text{A}$  Typ,  $V_{CC} = 5.5 \text{ V}$
- Balanced Output Drive:  $2 \text{ mA } I_{OL}$ ,  $-2 \text{ mA } I_{OH}$
- TTL-compatible Inputs
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

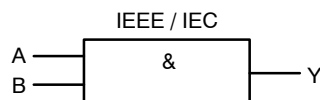
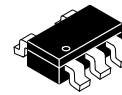
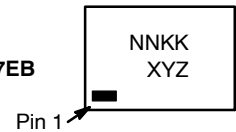


Figure 1. Logic Symbol

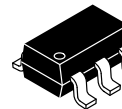
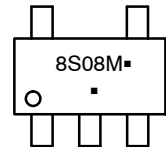
### MARKING DIAGRAMS



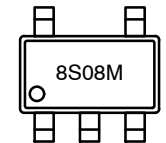
SIP6  
CASE 127EB



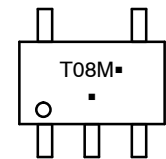
SC-74A  
CASE 318BQ



SOT23-5  
CASE 527AH



SC-88A  
CASE 419A-02



NN, 8S08, T08 = Specific Device Code  
 KK = 2-Digit Lot Run Traceability Code  
 XY = 2-Digit Date Code Format  
 Z = Assembly Plant Code  
 M = Date Code\*

\*Date Code orientation and/or position may vary depending upon manufacturing location.

### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 4 of this data sheet.

NOTE: Some of the devices on this data sheet have been **DISCONTINUED**. Please refer to the table on page 4.

# NC7ST08

## Pin Configurations

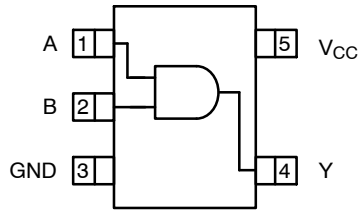


Figure 2. SOT23-5, SC-88A and SC-74A (Top View)

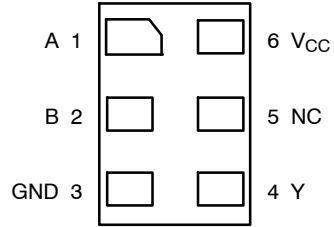


Figure 3. MicroPak (Top Through View)

## PIN DESCRIPTION

| Pin Names | Description |
|-----------|-------------|
| A, B      | Inputs      |
| Y         | Output      |
| NC        | No Connect  |

## FUNCTION TABLE (Y = AB)

| Inputs |   | Output |
|--------|---|--------|
| A      | B | Y      |
| L      | L | L      |
| L      | H | L      |
| H      | L | L      |
| H      | H | H      |

H = HIGH Logic Level  
L = LOW Logic Level

## ABSOLUTE MAXIMUM RATINGS

| Symbol                | Parameter                                    |                        | Min  | Max            | Unit |
|-----------------------|----------------------------------------------|------------------------|------|----------------|------|
| $V_{CC}$              | Supply Voltage                               |                        | -0.5 | 6.5            | V    |
| $I_{IK}$              | DC Input Diode Current                       | $V_{IN} < 0\text{ V}$  | -    | -20            | mA   |
|                       |                                              | $V_{IN} > V_{CC}$      | -    | +20            |      |
| $V_{IN}$              | DC Input Voltage                             |                        | -0.5 | $V_{CC} + 0.5$ | V    |
| $I_{OK}$              | DC Output Diode Current                      | $V_{OUT} < 0\text{ V}$ | -    | -20            | mA   |
|                       |                                              | $V_{OUT} > V_{CC}$     | -    | +20            |      |
| $V_{OUT}$             | Output Voltage                               |                        | -0.5 | $V_{CC} + 0.5$ | V    |
| $I_{OUT}$             | DC Output Source or Sink Current             |                        | -    | $\pm 12.5$     | mA   |
| $I_{CC}$ or $I_{GND}$ | DC $V_{CC}$ or Ground Current per Supply Pin |                        | -    | $\pm 25$       | mA   |
| $T_{STG}$             | Storage Temperature                          |                        | -65  | +150           | °C   |
| $T_J$                 | Junction Temperature                         |                        | -    | +150           | °C   |
| $T_L$                 | Lead Temperature (Soldering, 10 Seconds)     |                        | -    | +260           | °C   |
| $P_D$                 | Power Dissipation in Still Air               | SC-74A / SOT23-5       | -    | 390            | mW   |
|                       |                                              | SC-88A                 | -    | 332            |      |
|                       |                                              | MicroPak-6             | -    | 812            |      |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# RECOMMENDED OPERATING CONDITIONS

| Symbol                          | Parameter                | Conditions              | Min | Max             | Unit |
|---------------------------------|--------------------------|-------------------------|-----|-----------------|------|
| V <sub>CC</sub>                 | Supply Voltage           |                         | 4.5 | 5.5             | V    |
| V <sub>IN</sub>                 | Input Voltage            |                         | 0   | V <sub>CC</sub> | V    |
| V <sub>OUT</sub>                | Output Voltage           |                         | 0   | V <sub>CC</sub> | V    |
| T <sub>A</sub>                  | Operating Temperature    |                         | -40 | +85             | °C   |
| t <sub>r</sub> , t <sub>f</sub> | Input Rise and Fall Time | V <sub>CC</sub> = 5.0 V | 0   | 10              | ns/V |
| θ <sub>JA</sub>                 | Thermal Resistance       | SC-74A / SOT23-5        | -   | 320             | °C/W |
|                                 |                          | SC-88A                  | -   | 377             |      |
|                                 |                          | MicroPak-6              | -   | 154             |      |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.

## DC ELECTRICAL CHARACTERISTICS

| Symbol           | Parameter                 | V <sub>CC</sub> (V) | Conditions                                                                               | T <sub>A</sub> = +25°C |             |             | T <sub>A</sub> = -40 to +85°C |             | Unit |
|------------------|---------------------------|---------------------|------------------------------------------------------------------------------------------|------------------------|-------------|-------------|-------------------------------|-------------|------|
|                  |                           |                     |                                                                                          | Min                    | Typ         | Max         | Min                           | Max         |      |
| V <sub>IH</sub>  | HIGH Level Input Voltage  | 4.5 – 5.5           |                                                                                          | 2.0                    | -           | -           | 2.0                           | -           | V    |
| V <sub>IL</sub>  | LOW Level Input Voltage   | 4.5 – 5.5           |                                                                                          | -                      | -           | 0.8         | -                             | 0.8         | V    |
| V <sub>OH</sub>  | HIGH Level Output Voltage | 4.5<br>4.5          | I <sub>OH</sub> = -20 μA<br>I <sub>OH</sub> = -2 mA<br>V <sub>IN</sub> = V <sub>IH</sub> | 4.4<br>4.18            | 4.5<br>4.35 | -           | 4.4<br>4.13                   | -           | V    |
| V <sub>OL</sub>  | LOW Level Output Voltage  | 4.5<br>4.5          | I <sub>OL</sub> = 20 μA<br>I <sub>OL</sub> = 2 mA<br>V <sub>IN</sub> = V <sub>IL</sub>   | -                      | 0<br>0.10   | 0.1<br>0.26 | -                             | 0.1<br>0.33 | V    |
| I <sub>IN</sub>  | Input Leakage Current     | 5.5                 | 0 ≤ V <sub>IN</sub> ≤ 5.5 V                                                              | -                      | -           | ±0.1        | -                             | ±1.0        | μA   |
| I <sub>CC</sub>  | Quiescent Supply Current  | 5.5                 | V <sub>IN</sub> = V <sub>CC</sub> or GND                                                 | -                      | -           | 1.0         | -                             | 10.0        | μA   |
| I <sub>CCT</sub> | I <sub>CC</sub> per Input | 5.5                 | One Input V <sub>IN</sub> = 0.5 V or 2.4 V, Other Input V <sub>CC</sub> or GND           | -                      | -           | 2.0         | -                             | 2.9         | mA   |

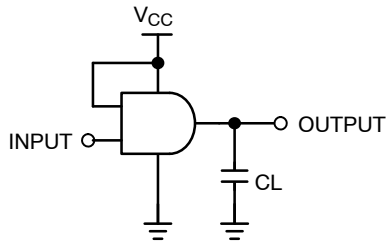
## AC ELECTRICAL CHARACTERISTICS

| Symbol                              | Parameter                                | V <sub>CC</sub> (V) | Conditions             | T <sub>A</sub> = +25°C |     |     | T <sub>A</sub> = -40 to +85°C |     | Unit |
|-------------------------------------|------------------------------------------|---------------------|------------------------|------------------------|-----|-----|-------------------------------|-----|------|
|                                     |                                          |                     |                        | Min                    | Typ | Max | Min                           | Max |      |
| t <sub>PLH</sub> , t <sub>PHL</sub> | Propagation Delay (Figure 4, 6)          | 5.0                 | C <sub>L</sub> = 15 pF | -                      | 4   | 12  | -                             | -   | ns   |
|                                     |                                          |                     |                        | -                      | 6   | 17  | -                             | -   |      |
|                                     |                                          | 4.5                 | C <sub>L</sub> = 50 pF | -                      | 6   | 16  | -                             | 20  |      |
|                                     |                                          |                     |                        | -                      | 12  | 27  | -                             | 31  |      |
|                                     |                                          | 5.5                 |                        | -                      | 5   | 14  | -                             | 18  |      |
|                                     |                                          |                     |                        | -                      | 11  | 26  | -                             | 30  |      |
| t <sub>TLH</sub> , t <sub>THL</sub> | Output Transition Time (Figure 4, 6)     | 5.0                 | C <sub>L</sub> = 15 pF | -                      | 4   | 10  | -                             | -   | ns   |
|                                     |                                          | 4.5                 | C <sub>L</sub> = 50 pF | -                      | 11  | 25  | -                             | 31  |      |
|                                     |                                          | 5.5                 |                        | -                      | 10  | 21  | -                             | 26  |      |
| C <sub>IN</sub>                     | Input Capacitance                        | Open                |                        | -                      | -   | 10  | -                             | -   | pF   |
| C <sub>PD</sub>                     | Power Dissipation Capacitance (Figure 5) | 5.0                 | (Note 2)               | -                      | 6   | -   | -                             | -   | pF   |

2. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current. Current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle. (See Figure 5) C<sub>PD</sub> is related to I<sub>CCD</sub> dynamic operating current by the expression: I<sub>CCD</sub> = (C<sub>PD</sub>) (V<sub>CC</sub>) (f<sub>IN</sub>) + (I<sub>CCstatic</sub>).

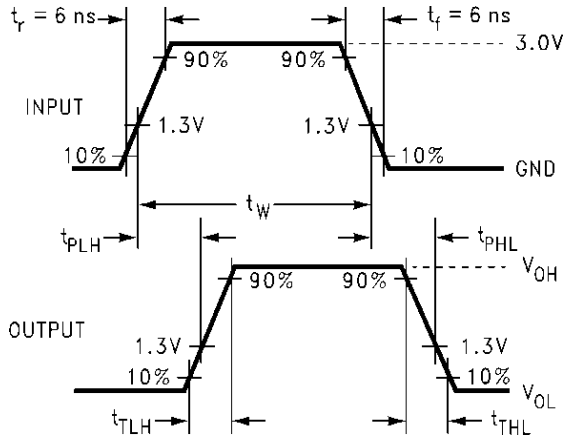
## NC7ST08

### AC Loading and Waveforms

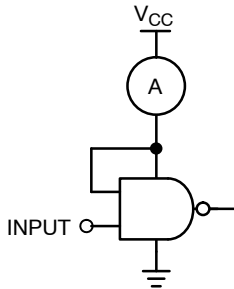


$C_L$  includes load and stray capacitance  
Input PRR = 1.0 MHz,  $t_W = 500$  ns

**Figure 4. AC Test Circuit**



**Figure 6. AC Waveforms**



Input = AC Waveform;  
PRR = Variable; Duty Cycle = 50%.

**Figure 5.  $I_{CCD}$  Test Circuit**

### DEVICE ORDERING INFORMATION

| Device     | Top Mark | Packages       | Shipping <sup>†</sup> |
|------------|----------|----------------|-----------------------|
| NC7ST08M5X | 8S08     | SC-74A         | 3000 / Tape & Reel    |
| NC7ST08P5X | T08      | SC-88A         | 3000 / Tape & Reel    |
| NC7ST08L6X | NN       | SIP6, MicroPak | 5000 / Tape & Reel    |

### DISCONTINUED (Note 3)

|                   |      |                |                    |
|-------------------|------|----------------|--------------------|
| NC7ST08M5X-L22090 | 8S08 | SOT23-5        | 3000 / Tape & Reel |
| NC7ST08P5X-L22057 | T08  | SC-88A         | 3000 / Tape & Reel |
| NC7ST08L6X-L22175 | NN   | SIP6, MicroPak | 5000 / Tape & Reel |

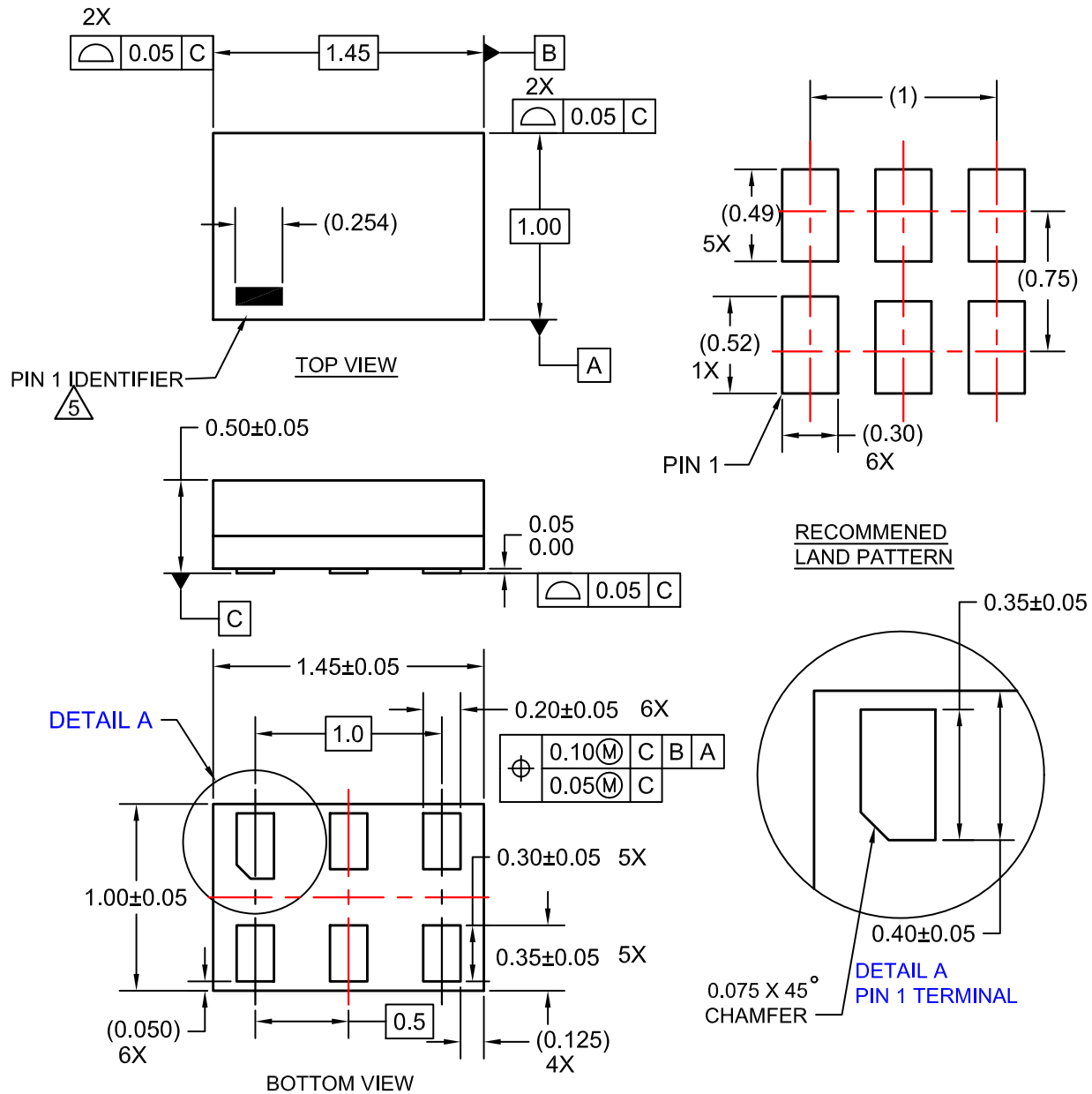
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

3. **DISCONTINUED:** These devices are not recommended for new design. Please contact your **onsemi** representative for information. The most current information on these devices may be available on [www.onsemi.com](http://www.onsemi.com).

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**SIP6 1.45X1.0**  
CASE 127EB  
ISSUE O

DATE 31 AUG 2016

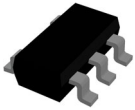


## NOTES:

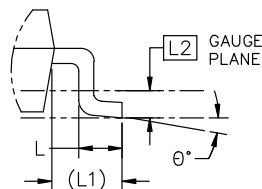
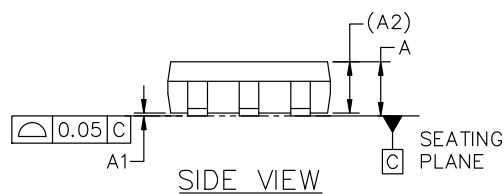
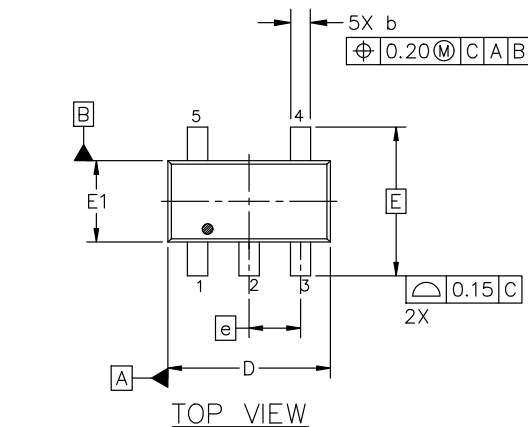
1. CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y14.5M-2009
4. PIN ONE IDENTIFIER IS 2X LENGTH OF ANY OTHER LINE IN THE MARK CODE LAYOUT.

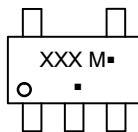
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**SC-74A-5 3.00x1.50x0.95, 0.95P**  
**CASE 318BQ**  
**ISSUE C**

DATE 26 FEB 2024


DETAIL "A"  
SCALE 2:1

**GENERIC**  
**MARKING DIAGRAM\***


XXX = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

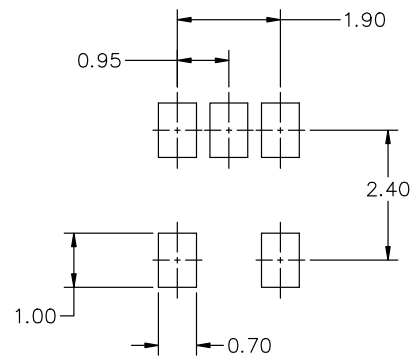
(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

## NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSION ARE IN MILLIMETERS (ANGLES IN DEGREES).
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OF GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

| DIM | MILLIMETERS |      |      |
|-----|-------------|------|------|
|     | MIN.        | NOM. | MAX. |
| A   | 0.90        | 1.00 | 1.10 |
| A1  | 0.01        | 0.18 | 0.10 |
| A2  | 0.95 REF.   |      |      |
| b   | 0.25        | 0.37 | 0.50 |
| c   | 0.10        | 0.18 | 0.26 |
| D   | 2.85        | 3.00 | 3.15 |
| E   | 2.75 BSC    |      |      |
| E1  | 1.35        | 1.50 | 1.65 |
| e   | 0.95 BSC    |      |      |
| L   | 0.20        | 0.40 | 0.60 |
| L1  | 0.62 REF.   |      |      |
| L2  | 0.25 BSC    |      |      |
| θ   | 0°          | 5°   | 10°  |



## RECOMMENDED MOUNTING FOOTPRINT\*

\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

|                         |                                       |                                                                                                                                                                                  |
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| <b>DESCRIPTION:</b>     | <b>SC-74A-5 3.00x1.50x0.95, 0.95P</b> | <b>PAGE 1 OF 1</b>                                                                                                                                                               |

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SCALE 2:1

**SC-88A (SC-70-5/SOT-353)**  
CASE 419A-02  
ISSUE M

DATE 11 APR 2023

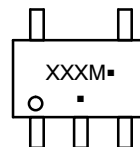

**RECOMMENDED  
MOUNTING FOOTPRINT**

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. 419A-01 OBSOLETE. NEW STANDARD 419A-02
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

| DIM | MILLIMETERS |      |      |
|-----|-------------|------|------|
|     | MIN.        | NOM. | MAX. |
| A   | 0.80        | 0.95 | 1.10 |
| A1  | ---         | ---  | 0.10 |
| A3  | 0.20 REF    |      |      |
| b   | 0.10        | 0.20 | 0.30 |
| c   | 0.10        | ---  | 0.25 |
| D   | 1.80        | 2.00 | 2.20 |
| E   | 2.00        | 2.10 | 2.20 |
| E1  | 1.15        | 1.25 | 1.35 |
| e   | 0.65 BSC    |      |      |
| L   | 0.10        | 0.15 | 0.30 |

**GENERIC MARKING  
DIAGRAM\***


\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code

M = Date Code

▪ = Pb-Free Package

(Note: Microdot may be in either location)

**STYLE 1:**

- PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

**STYLE 2:**

- PIN 1. ANODE
2. EMITTER
3. BASE
4. COLLECTOR
5. CATHODE

**STYLE 3:**

- PIN 1. ANODE 1
2. N/C
3. ANODE 2
4. CATHODE 2
5. CATHODE 1

**STYLE 4:**

- PIN 1. SOURCE 1
2. DRAIN 1/2
3. SOURCE 1
4. GATE 1
5. GATE 2

**STYLE 5:**

- PIN 1. CATHODE
2. COMMON ANODE
3. CATHODE 2
4. CATHODE 3
5. CATHODE 4

**STYLE 6:**

- PIN 1. EMITTER 2
2. BASE 2
3. EMITTER 1
4. COLLECTOR
5. COLLECTOR 2/BASE 1

**STYLE 7:**

- PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

**STYLE 8:**

- PIN 1. CATHODE
2. COLLECTOR
3. N/C
4. BASE
5. EMITTER

**STYLE 9:**

- PIN 1. ANODE
2. CATHODE
3. ANODE
4. ANODE
5. ANODE

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

|                         |                                 |                                                                                                                                                                                  |
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| <b>DESCRIPTION:</b>     | <b>SC-88A (SC-70-5/SOT-353)</b> | <b>PAGE 1 OF 1</b>                                                                                                                                                               |

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**SOT-23, 5 Lead**  
**CASE 527AH**  
**ISSUE A**

DATE 09 JUN 2021

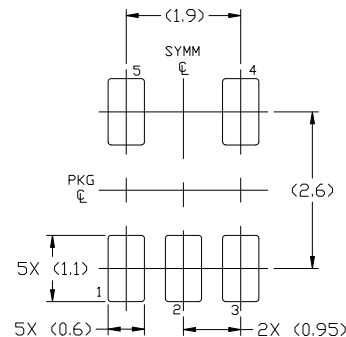

XXX = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1989A
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.25 PER SIDE. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM D.
5. DIMENSION 'b' DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE 'b' DIMENSION AT MAXIMUM MATERIAL CONDITION. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL NOT BE LESS THAN 0.07mm.

| DIM | MILLIMETERS |      |      |
|-----|-------------|------|------|
|     | MIN.        | NOM. | MAX. |
| A   | 0.90        | —    | 1.45 |
| A1  | 0.00        | —    | 0.15 |
| A2  | 0.90        | 1.15 | 1.30 |
| b   | 0.30        | —    | 0.50 |
| c   | 0.08        | —    | 0.22 |
| D   | 2.90 BSC    |      |      |
| E   | 2.80 BSC    |      |      |
| E1  | 1.60 BSC    |      |      |
| e   | 0.95 BSC    |      |      |
| L   | 0.30        | 0.45 | 0.60 |
| L1  | 0.60 REF    |      |      |
| L2  | 0.25 REF    |      |      |
| θ   | 0°          | 4°   | 8°   |
| θ1  | 0°          | 10°  | 15°  |
| θ2  | 0°          | 10°  | 15°  |


**RECOMMENDED**  
**MOUNTING FOOTPRINT**

For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

|                         |                       |                                                                                                                                                                                  |
|-------------------------|-----------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
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| <b>DESCRIPTION:</b>     | <b>SOT-23, 5 LEAD</b> | <b>PAGE 1 OF 1</b>                                                                                                                                                               |

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